

0083-0865-2

IN THE UNITED STATES PATENT & TRADEMARK OFFICE

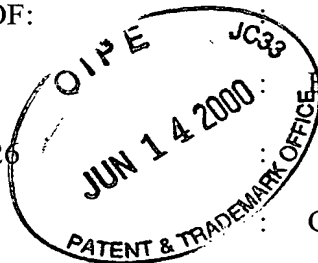
IN RE APPLICATION OF:

Masashi GOTOH, et al.

SERIAL NO.: 09/119,626

FILED: July 21, 1998

FOR: CIRCUIT BOARD HAVING
BONDING AREAS TO BE
JOINED WITH BUMPS BY
ULTRASONIC BONDING



EXAMINER: CUNEO, K.

GROUP ART UNIT: 2831

14/A

6-21-00

T. Flowers

AMENDMENT

ASSISTANT COMMISSIONER FOR PATENTS
WASHINGTON, D.C. 20231

SIR:

In response to the Official Action dated March 16, 2000, please amend the above-identified application as follows:

IN THE SPECIFICATION

Please amend the specification as follows:

Page 10, line 16, after "margin" insert --4c--; and

line 17, after "inside" insert --4d--.

Page 14, lines 10-18, delete in their entirety and insert the following:

--In the description of the first embodiment, the conductive layer 3 is described as being etched to form slits for the notch parts 8a and 8b. In such a process, during the formation of the thick-film conductive layer, masking is executed through a screen so that the screen prevents the depositing of portions of the thick-film conductive layer on the board main body where the notch parts are located. Of course, the notch parts 8a and 8b can also be

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